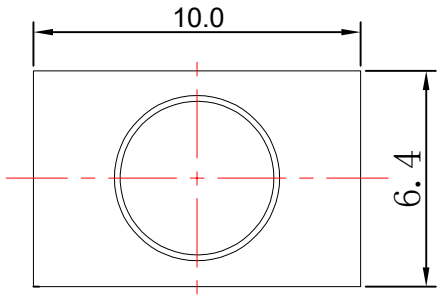
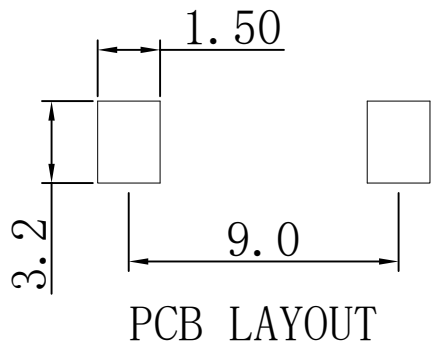
RoHS

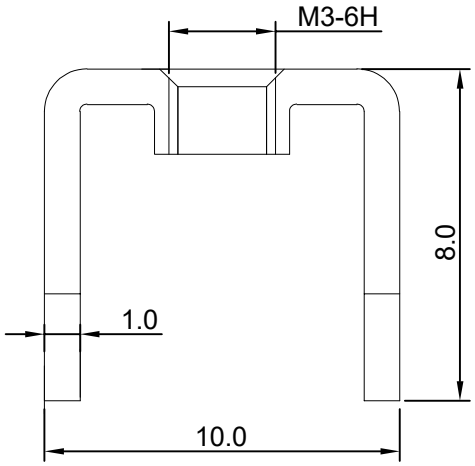
REV.	ECN NO.	DESCRIPTION	DESIGN	APPROVAL	DATE
A1	NEW	更换图框			2024.04.23

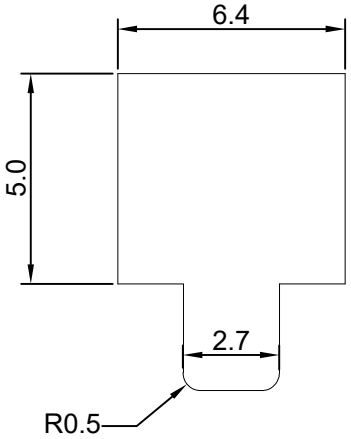




PCB LAYOUT

技术要求：
1.打铜底0.5-1μm,镍1-2μm，镀哑锡3-5μm。
2.铆好后不得有松动现象。
3.插脚尖部符合可焊性要求。
4.螺纹需符合通止规/止针要求。
5.螺纹扭矩：0.7Nm.
6.额定电流 ：50A.





1	插脚		H62(Y2)	1
序号	名称	零件编号	材质	数量

＞30.±0.4	X.°±
6-30±0.3	.X°±
0-6±0.2	.XX°±
ANGLES±1°	.XXX°±
UNITS:	mm

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PART NO: T32100064-0800

TITLE: PCB SOLDERING TERMINAL

APPD	Chen ZhiQiang
CHKD	Liu Wei
DRAW	Chen HongJiang
DATE	2024.04.23

XFCN 兴飞连接器
0769-82001899
www.xfconn.com

DWG NO: /

VIEW		
SCALE	SHEET	REV
NONE	1/1	A1